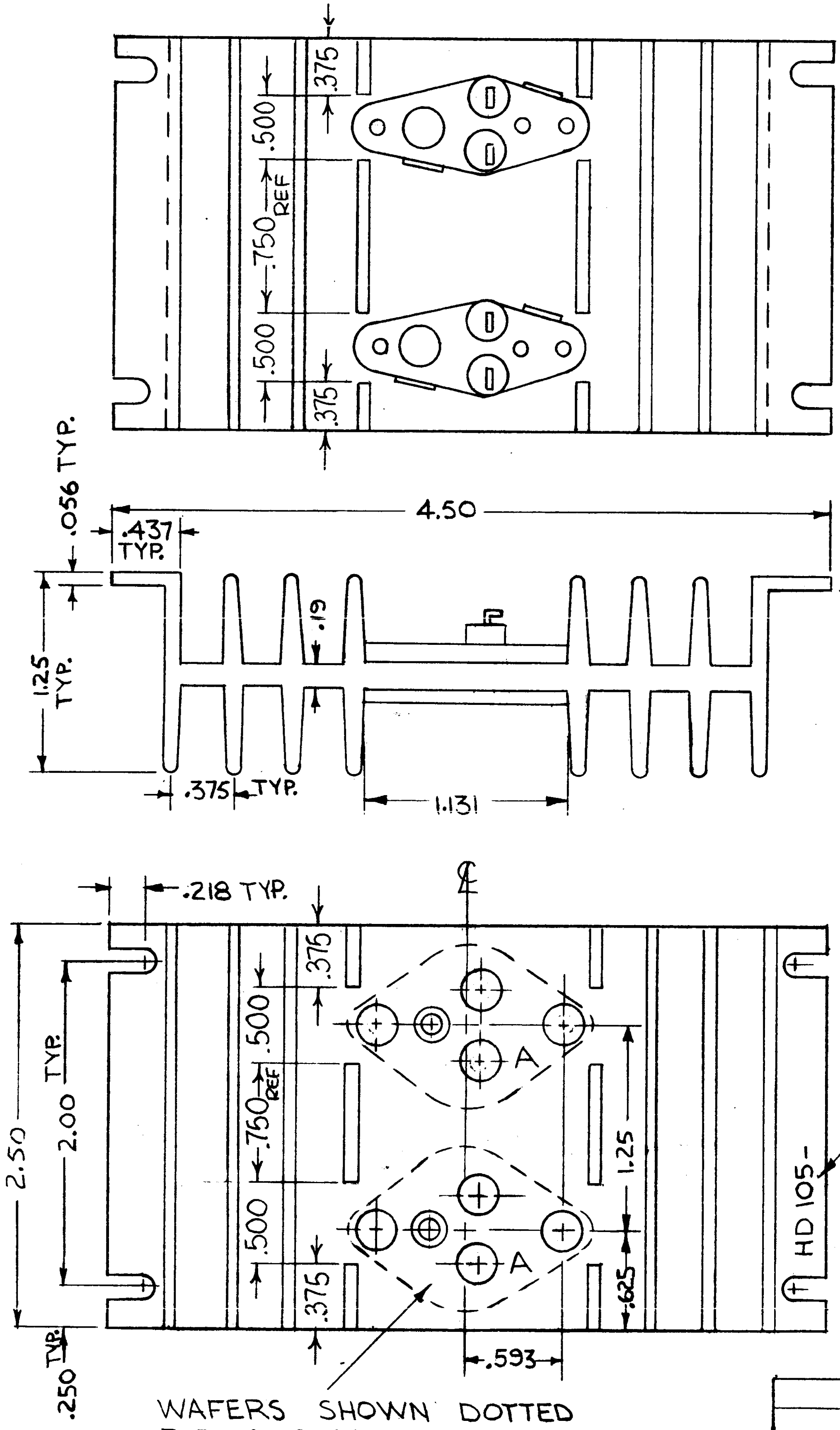
STANDARD DRAWING

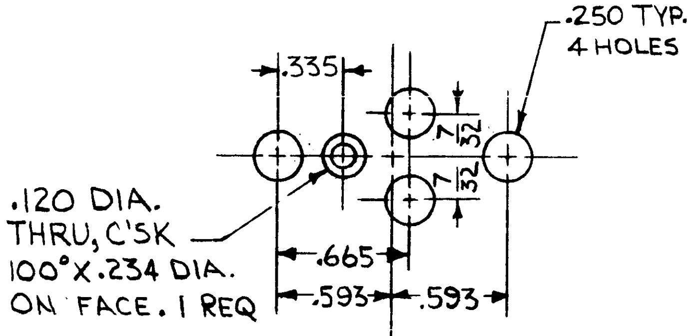
HD105 A

REVISIONS						
SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD	APPD
X	EXPERIMENTAL RELEASE	9·30·66	X	RME		
Ø	ORIG RELEASE FOR PROD	10/11/66	Ø	CV		
A	2.00 DIM WAS 2.25, NOTE 4 WAS 8080-161	10/30/67	18576	H.G.		EFM



WAFERS SHOWN DOTTED FOR CLARITY.

MARK TMC PART/NO. 1/8 HIGH GOTHIC W/LATEST REVISION LETTER.



DETAIL "A"
(2 REQ)

NOTES:

1- WAFER MATERIAL: BERYLLIUM OXIDE.
2- SURFACE FOR BERYLLIUM OXIDE WAFER MUST BE FLAT.
3- SOCKET & WAFER TO ACCEPT TO-3 TYPE SEMI-CONDUCTOR.
4- SOCKET - AUGAT 8043 -1G3 OR EQUIV.

Q'T'Y./UNIT	MODEL USED ON	ASS'Y. NO.
1	MSAR-4	
1	CFA-2	A4347

SCALE	CODE	
1:1	C	S401 - 408 (MODEL 13 MODIFIED)

THE CONTENTS OF THIS DRAWING ARE THE EXCLUSIVE PROPERTY OF THE TECHNICAL MATERIEL CORP. ITS UNAUTHORIZED USE OR REPRODUCTION IN WHOLE OR IN PART IS STRICTLY FORBIDDEN.

NOTES

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL

LIST OF MATERIAL

MATERIAL: ALUMINUM 6063-T6

FINISH: BLACK ANODIZE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES

DECIMALS	TOLERANCES	FRACTIONS
.X ± .05 .XX ± .01 .XXX ± .005	TOLERANCES	± 1/64 ANGLES ± 0° 30'

THE TECHNICAL MATERIEL CORP.
MAMARONECK, NEW YORK

TITLE: HEAT SINK, SEMI-CONDUCTOR

DRAWN RME	DATE 9·30·66	FINAL APPROV.	DATE 10/11/66
CHECKED	DATE		
ELECT. DES.	DATE	HD105	A
MECH. DES.	DATE 10/7/66	SHEET	REV. LTR.

TMC FORM 1 9

REPROVEL N . 440H 23858